

In the Claims

CLAIMS

Claims 1-30 (Canceled).

31. (Currently amended) An engagement probe comprising semiconductor bulk substrate material, the probe having a grouping of a plurality of projecting apices positioned in sufficient proximity to one another to collectively removably engage a plurality of different single conductive pads on a plurality of different semiconductor substrates to test circuitry coupled with the single conductive pads, wherein the plurality of the projecting apices engage only a single one of the conductive pads at a given moment in time.

32. (Previously presented) The engagement probe of claim 31 wherein the plurality of the projecting apices comprises linear portions which are arranged in an interconnecting structure, and wherein the plurality of the projecting apices lack terminal ends.

33. (Currently amended) The engagement probe of claim 31 wherein the projecting apices are in the shape of ~~multiple~~ knife-edge lines.

34. (Currently amended) The engagement probe of claim 31 wherein the projecting apices are in the shape of ~~multiple~~ knife-edge lines, the ~~multiple~~ knife-edge lines being positioned to form at least one polygon.

35. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes comprise outermost portions which constitute a first electrically conductive material, and wherein the respective different single conductive pads for which the probe is adapted have outermost portions constituting a second electrically conductive material; the first and second electrically conductive materials being different.

36. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes project from a common plane, the projecting apexes having respective tips and bases, the bases of adjacent projecting apexes being spaced from one another to define a penetration stop plane therebetween.

37. (Previously presented) The engagement probe of claim 31 wherein the projecting apexes have a selected projecting distance, the projecting distance being about one-half the thickness of the respective different single conductive pads which the apparatus is adapted to engage.

38. (Currently amended) The engagement probe of claim 31 wherein the projecting apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form the interconnecting structure comprising at least two polygons one of which is received entirely within the other.

39. (Previously presented) The engagement probe of claim 31 wherein the semiconductor bulk substrate material comprises silicon.

40. (Previously presented) The engagement probe of claim 31 wherein the semiconductor bulk substrate material comprises monocrystalline silicon.

41. (Previously presented) The engagement probe of claim 31 wherein the semiconductor bulk substrate material comprises material of a semiconductor wafer.

42. (New) The engagement probe of claim 31 wherein the plurality of the projecting apexes comprises semiconductive material.

43. (New) The engagement probe of claim 31 wherein individual ones of the projecting apexes comprise silicon.

44. (New) The engagement probe of claim 31 wherein individual ones of the projecting apexes comprise material of the substrate.

45. (New) The engagement probe of claim 31 wherein individual ones of the projecting apexes surround an exposed portion of the substrate.

46. (New) The engagement probe of claim 31 wherein at least some of the plurality of the projecting apexes comprise uppermost portions that extend linearly in different directions.

47. (New) The engagement probe of claim 46 wherein the different directions are substantially perpendicular to one another.

48. (New) An engagement probe comprising semiconductor bulk substrate material, the probe having a grouping of a plurality of projecting apexes positioned in sufficient proximity to one another to collectively removably engage a plurality of different single conductive pads on a plurality of different semiconductor substrates to test circuitry coupled with the single conductive pads; and

wherein the plurality of the projecting apexes comprises linear portions which are arranged in an interconnecting structure, and wherein the plurality of the projecting apexes lack terminal ends.

49. (New) An engagement probe comprising semiconductor bulk substrate material, the probe having a grouping of a plurality of projecting apexes positioned in sufficient proximity to one another to collectively removably engage a plurality of different single conductive pads on a plurality of different semiconductor substrates to test circuitry coupled with the single conductive pads; and

wherein the projecting apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form at least one polygon.

50. (New) An engagement probe comprising semiconductor bulk substrate material, the probe having a grouping of a plurality of projecting apexes positioned in sufficient proximity to one another to collectively removably engage a plurality of different single conductive pads on a plurality of different semiconductor substrates to test circuitry coupled with the single conductive pads; and

wherein the projecting apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form the interconnecting structure comprising at least two polygons one of which is received entirely within the other.